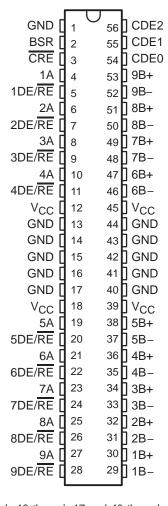
- Improved Speed and Package Replacement for the SN75LBC976
- Designed to Operate at up to 20 Million
 Data Transfers per Second (Fast-20 SCSI)
- Nine Differential Channels for the Data and Control Paths of the Small Computer Systems Interface (SCSI) and Intelligent Peripheral Interface (IPI)
- SN75976A Packaged in Shrink Small-Outline Package with 25-Mil Terminal Pitch (DL) and Thin Shrink Small-Outline Package with 20-Mil Terminal Pitch (DGG)
- SN55976A Packaged in a 56-Pin Ceramic Flat Pack (WD)
- Two Skew Limits Available
- ESD Protection on Bus Terminals Exceeds 12 kV
- Low Disabled Supply Current 8 mA Typ
- Thermal Shutdown Protection
- Positive- and Negative-Current Limiting
- Power-Up/Down Glitch Protection

description

The SN75976A is an improved replacement for industry's first 9-channel RS-485 the transceiver — the SN75LBC976. The A version offers improved switching performance, a smaller package, and higher ESD protection. The SN75976A is offered in two versions. The '976A2 skew limits of 4 ns for the differential drivers and 5 ns for the differential receivers complies with the recommended skew budget of the Fast-20 SCSI standard for data transfer rates up to 20 million transfers per second. The '976A1 supports the Fast SCSI skew budget for 10 million

SN75976A DGG or DL SN55976A WD (TOP VIEW)



Terminals 13 through 17 and 40 through 44 are connected together to the package lead frame and signal ground.

transfers per second. The skew limit ensures that the propagation delay times, not only from channel-to-channel but from device-to-device, are closely matched for the tight skew budgets associated with high-speed parallel data buses.

The patented thermal enhancements made to the 56-pin shrink small-outline package (SSOP) of the SN75976 have been applied to the new, thin shrink, small-outline package (TSSOP). The TSSOP package offers even less board area requirements than the SSOP while reducing the package height to 1 mm. This provides more board area and allows component mounting to both sides of the printed circuit boards for low-profile, space-restricted applications such as small form-factor hard disk drives.



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SN75976A, SN55976A 9-CHANNEL DIFFERENTIAL TRANSCEIVER

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description (continued)

In addition to speed improvements, the '976A can withstand electrostatic discharges exceeding 12 kV using the human-body model, and 600 V using the machine model of MIL-PRF-38535, Method 3015.7 on the RS-485 I/O terminals. This is six times the industry standard and provides protection from the noise that can be coupled into external cables. The other terminals of the device can withstand discharges exceeding 4 kV and 400 V respectively.

Each of the nine channels of the '976A typically meet or exceed the requirements of EIA RS-485 (1983) and ISO 8482-1987/TIA TR30.2 referenced by American National Standard of Information (ANSI) Systems, X3.131-1994 (SCSI-2) standard, X2.277-1996 (Fast-20 Parallel Interface), and the Intelligent Peripheral Interface Physical Layer-ANSI X3.129-1986 standard.

The SN75976A is characterized for operation over an ambient air temperature range of 0° C to 70° C. The SN55976A is characterized for operation over an ambient air temperature range of -55° C to 125° C.

AVAILABLE OPTIONS

| т. | Skew Limit (ns) | | PACKAGE [†] | | | | | |
|----------------|--------------------|---|-------------------------------|-----------------------------|---------------------------|--|--|--|
| TA | Driver Receiver | | TSSOP (DGG) | SSOP (DL) | CERAMIC FLAT PACK (WD) | | | |
| 0°C to 70°C | 8 | 9 | SN75976A1DGG SN75976A1DGGR | SN75976A1DL SN75976A1DLR | _ | | | |
| 0°C to 70°C | 4 | 5 | SN75976A2DGG SN75976A2DGGR | SN75976A2DL SN75976A2DLR | _ | | | |
| -55°C to 125°C | 8 | 9 | | _ | SN55976A1WD | | | |
| -55 0 10 125 0 | 4 | 5 | _ | | SN55976A2WD | | | |

[†]The R suffix indicates taped and reeled packages.

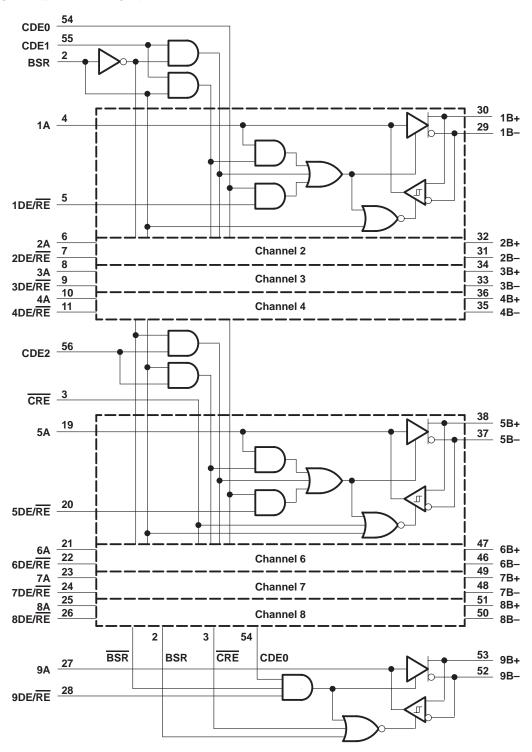


Terminal Functions

| TERM | INAL | Logic | | T | DECORPTION |
|---------------------|---|--------|-------|-------------|---|
| NAME | NO. | Level | 1/0 | Termination | DESCRIPTION |
| 1A to 9A | 4,6,8,10, 19,21,23, 25,27 | TTL | I/O | Pullup | 1A to 9A carry data to and from the communication controller. |
| 1B- to 9B- | 29,31,33, 35,37,.46, 48,50,52 | RS-485 | I/O | Pulldown | 1B- to 9B- are the inverted data signals of the balanced pair to/from the bus. |
| 1B+ to 9B+ | 30,32,34, 36,38,47, 49,51,53 | RS-485 | I/O | Pullup | 1B+ to 9B+ are the noninverted data signals of the balanced pair to/from the bus. |
| BSR | 2 | TTL | Input | Pullup | BSR is the bit significant response. BSR disables receivers 1 through 8 and enables wired-OR drivers when BSR and DE/RE and CDE1 or CDE2 are high. Channel 9 is placed in a high-impedance state with BSR high. |
| CDE0 | 54 | TTL | Input | Pulldown | CDE0 is the common driver enable 0. Its input signal enables all drivers when CDE0 and 1DE/RE – 9DE/RE are high. |
| CDE1 | 55 | TTL | Input | Pulldown | CDE1 is the common driver enable 1. Its input signal enables drivers 1 to 4 when CDE1 is high and BSR is low. |
| CDE2 | 56 | TTL | Input | Pulldown | CDE2 is the common driver enable 2. When CDE2 is high and BSR is low, drivers 5 to 8 are enabled. |
| CRE | 3 | TTL | Input | Pullup | CRE is the common receiver enable. When high, CRE disables receiver channels 5 to 9. |
| 1DE/RE to 9DE/RE | 5,7,9,11, 20,22,24, 26,28 | TTL | Input | Pullup | 1DE/RE-9DE/RE are direction controls that transmit data to the bus when it and CDE0 are high. Data is received from the bus when 1DE/RE-9DE/RE and CRE and BSR are low and CDE1 and CDE2 are low. |
| GND | 1,13,14, 15,16,17, 40,41,42, 43,44 | NA | Power | NA | GND is the circuit ground. All GND terminals except terminal 1 are physically tied to the die pad for improved thermal conductivity.† |
| VCC | 12,18,39, 45 | NA | Power | NA | Supply voltage |

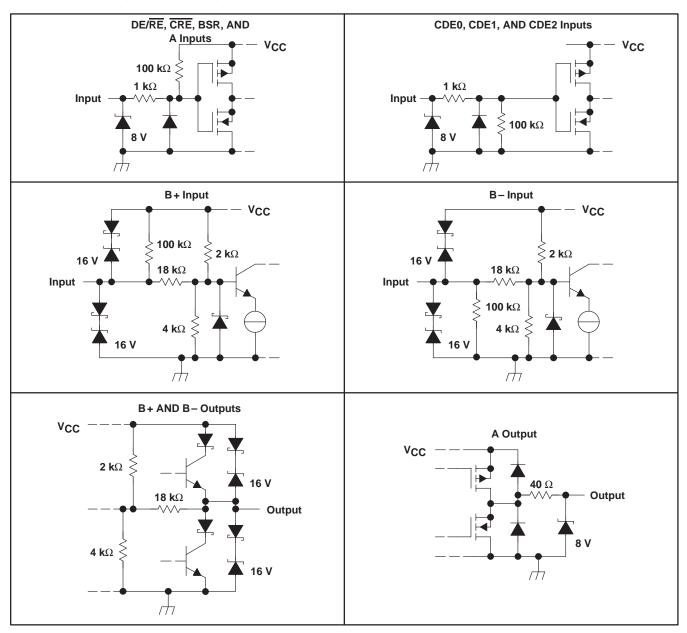
[†] Terminal 1 must be connected to signal ground for proper operation.

logic diagram (positive logic)





schematics of inputs and outputs



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

| Supply voltage range, V _{CC} (see Note 1) | 0.3 V to 6 V |
|--|--|
| Bus voltage range | $\dots \dots -10 \ V$ to 15 V |
| Data I/O and control (A side) voltage range | \dots -0.3 V to V _{CC} +0.5 V |
| Electrostatic discharge: B side and GND, Class 3, A: (see Note 2 | |
| | 2) 400 V |
| All terminals, Class 3, A: | 4 kV |
| | 400 V |
| Continuous total power dissipation (see Note 3) | |
| Storage temperature range, T _{stq} | |
| Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds | 260°C |

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values are with respect to the GND terminals.
 - 2. This absolute maximum rating is tested in accordance with MIL-PRF-38535, Method 3015.7.
 - 3. The maximum operating junction temperature is internally limited. Use the Dissipation Rating Table to operate below this temperature.

DISSIPATION RATING TABLE

| PACKAGE | $T_{\mbox{\scriptsize A}} \leq 25^{\circ} \mbox{\scriptsize C}$ | OPERATING FACTOR [‡] ABOVE T _A = 25°C | T _A = 70°C POWER RATING | T _A = 125°C POWER RATING |
|---------|---|--|---------------------------------------|--|
| DGG | 2500 mW | 20 mW/°C | 1600 mW | _ |
| DL | 2500 mW | 20 mW/°C | 1600 mW | _ |
| WD | 1300 mW | 10.5 mW/°C | 827 mW | 250 mW |

[‡] This is the inverse of the junction-to-ambient thermal resistance when board-mounted and with no air flow.

package thermal characteristics

| | | MIN NO | MAX | UNIT |
|---|---------------------------------|--------|-----|------|
| lunction to embient thermal registeres. Be us | DGG, board-mounted, no air flow | 5 | 0 | °C/W |
| Junction-to-ambient thermal resistance, R ₀ J _A | | 5 | 0 | °C/W |
| Junction-to-ambient thermal resistance, R _{0JA} | WD | 95 | 4 | °C/W |
| Junction-to-case thermal resistance, RAJC | DGG | 2 | 7 | °C/W |
| Junction-to-case thermal resistance, K ₀ JC | DL | 1 | 2 | °C/W |
| Junction-to-case thermal resistance, R _{θJC} | WD | 5.6 | 7 | °C/W |
| Thermal-shutdown junction temperature, T _{JS} | | 16 | 5 | °C |



recommended operating conditions

| | | MIN | NOM | MAX | UNIT |
|---|------------------|------|-----|------|------|
| Supply voltage, V _{CC} | | 4.75 | 5 | 5.25 | V |
| High-level input voltage, V _{IH} | Except nB+, nB-† | 2 | | | V |
| Low-level input voltage, V _{IL} | Except nB+, nB-† | | | 0.8 | V |
| Voltage at any bus terminal (separately or common-mode), VO, VI, or VIC | nB+ or nB – | | | 12 | V |
| 7 | IID+ OI IID - | | | -7 | V |
| High-level output current, IOH | Driver | | | -60 | mA |
| Trigit-level output current, IOH | 7. C. I. I. | | | -8 | mA |
| Low lovel output output lev | Driver | | | 60 | mA |
| Low-level output current, IOL | Receiver | | | 8 | mA |
| Operating case temperature, T _C | SN75976A | 0 | | 125 | °C |
| One stating free cir temperature T. | SN75976A | 0 | | 70 | °C |
| Operating free-air temperature, T _A | SN55976A | -55 | | 125 | °C |

 $tar{1} = 1 - 9$

SN75976A, SN55976A 9-CHANNEL DIFFERENTIAL TRANSCEIVER

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| | DADAMETED | ١. | TEST CONDI | FIGNE | s | N55976 | A | S | N75976 | A | UNIT |
|-------------------|--|-----------------------------------|------------------------|--|------|---------------------|------|------|---------------------|------------------|------|
| | PARAMETER | ' | EST CONDIT | IIONS | MIN | TYP [†] | MAX | MIN | TYP [†] | MAX | UNII |
| | | S1 to A, | $V_T = 5 V$, | See Figure 1 | 0.7 | | | 1 | 1.8 | | V |
| VODH | Driver differential high- level output voltage | S1 to B, T _C ≥ 25°C | | V _T = 5 V, See Figure 1 | | | | 1 | 1.4 | | V |
| | , , | S1 to B, See Figure 1 | | V _T = 5 V, | 0.7 | | | 0.8 | | | V |
| | Delega effective fallow | S1 to A, T _C ≥ 25°C | | V _T = 5 V, See Figure 1 | 0.7 | -1.4 | | -1 | -1.4 | | V |
| VODL | Driver differential low- level output voltage | S1 to B, | $V_T = 5 V$, | See Figure 1 | 0.7 | -1.8 | | -1 | -1.8 | | V |
| | | S1 to A, See Figure 1 | | V _T = 5 V, | -0.8 | -1.4 | | -0.8 | -1.4 | | V |
| Vон | High-level output volt- | A side, IOH = -8 mA | | V _{ID} = 200 mV, See Figure 3 | 4 | 4.5 | | 4 | 4.5 | | V |
| | | B side, | $V_T = 5 V$, | See Figure 1 | | 3 | | | 3 | | V |
| VOL | Low-level output volt- | A side, I _{OH} = 8 mA | | V _{ID} = -200 mV, See Figure 3 | | 0.6 | 0.8 | | 0.6 | 0.8 | V |
| | | A side, | $V_T = 5 V$, | See Figure 1 | | 1 | | | 1 | | V |
| V _{IT+} | Receiver positive-go- ing differential input threshold voltage | $I_{OH} = -8 \text{ mA},$ | | See Figure 3 | | | 0.2 | | | 0.2 | V |
| V _{IT} _ | Receiver negative- going differential input threshold voltage | I _{OL} = 8 mA, | | See Figure 3 | | | -0.2 | | | -0.2 | V |
| V _{hys} | Receiver input hysteresis (V _{IT+} - V _{IT-}) | V _{CC} = 5 V, | | T _A = 25°C | 24 | 45 | | 24 | 45 | | mV |
| | | V _{IH} = 12 V, | V _{CC} = 5 V, | Other input at 0 V | | 0.4 | 1 | | 0.4 | 1 | mA |
| l | Bus input current | V _{IH} = 12 V, | V _{CC} = 0, | Other input at 0 V | | 0.5 | 1 | | 0.5 | 1 | mA |
| וי | bus input current | $V_{IH} = -7 V$, | | Other input at 0 V | | -0.4 | -0.8 | | -0.4 | -0.8 | mA |
| | | $V_{IH} = -7 V$, | $V_{CC} = 0$, | Other input at 0 V | | -0.3 | -0.8 | | -0.3 | -0.8 | mA |
| ήн | High-level input cur- | A, BSR, DE/R | E, and CRE, | V _{IH} = 2 V | | | -100 | | | -100 | μΑ |
| 'IH | rent | CDE0, CDE1, | and CDE2, | V _{IH} = 2V | | | 100 | | | 100 | μΑ |
| ΙΙL | Low-level input current | A, BSR, DE/R | E, and CRE, | V _{IL} = 0.8 V | | | -100 | | | -100 | μΑ |
| '1L | Low-level input current | CDE1, CDE1, | and CDE2, | V _{IL} = 0.8 V | | | 100 | | | 100 | μΑ |
| los | Short circuit output current | nB+ or nB– | | | | | ±260 | | | ±260 | mA |
| 107 | High-impedance-state | А | | | See | I _{IH} and | IIL | See | I _{IH} and | I _I L | |
| loz | output current | nB+ or nB- | | | | See I _I | | | See I _I | | |
| | | Disabled | | | | | 10 | | | 10 | mA |
| ICC | Supply current | All drivers ena | bled, no load | | | | 60 | | | 60 | mA |
| | | All receivers e | nabled, no loa | ad | | | 45 | | | 45 | mA |
| CO | Output capacitance | nB+ or nB- to | GND | | | 18 | | | 18 | 25 | pF |
| C _{pd} | Power dissipation capacitance | Receiver | | | | 40 | | | 40 | | pF |
| - pu | (see Note 4) | Driver | | | | 100 | | | 100 | | pF |

† All typical values are at V_{CC} = 5 V, T_A = 25°C. NOTE 4: C_{pd} determines the no-load dynamic supply current consumption, I_S = $C_{PD} \times V_{CC} \times f + I_{CC}$



driver switching characteristics over recommended operating conditions (unless otherwise noted)

| | PARAMETER | | | NDITIONS | S | N75976A | \ | UNIT |
|----------------------|---|--------|---------------------|------------------------|-----|---------|------|------|
| | PARAMETER | | l lesi co | MDITIONS | MIN | TYP† | MAX | UNIT |
| | | | | | 2.5 | | 13.5 | ns |
| | | '976A1 | $V_{CC} = 5 V$, | $T_C = 25^{\circ}C$ | 3 | | 11 | ns |
| t _{on at} | Propagation delay time, tpHL or tpLH | | $V_{CC} = 5 V$, | T _C = 100°C | 5 | | 13 | ns |
| ^t pd | (see Figures 1 and 2) | | | | 4.5 | | 11.5 | ns |
| | | '976A2 | $V_{CC} = 5 V$, | $T_C = 25^{\circ}C$ | 5 | | 9 | ns |
| | | | $V_{CC} = 5 V$, | T _C = 100°C | 7 | | 11 | ns |
| + \ | Skew limit, maximum t _{pd} – minimum t _{pd} | '976A1 | | | | | 8 | ns |
| ^t sk(lim) | (see Note 5) | '976A2 | | | | | 4 | ns |
| t _{sk(p)} | Pulse skew, t _{PHL} - t _{PLH} | | | | | | 4 | ns |
| t _f | Fall time | | S1 to B, | See Figure 2 | | 4 | | ns |
| t _r | Rise time | | See Figure 2 | | | 8 | | ns |
| t _{en} | Enable time, control inputs to active output | | | | | | 50 | ns |
| tdis | Disable time, control inputs to high-impedance output | t | | | | | 100 | ns |
| ^t PHZ | HZ Propagation delay time, high-level to high-impedance output | | See Figures 5 and 6 | | | 17 | 100 | ns |
| t _{PLZ} | tPLZ Propagation delay time, low-level to high-impedance output | | | | | 25 | 100 | ns |
| ^t PZH | | | | | | 17 | 50 | ns |
| tPZL | Propagation delay time, high-impedance to low-level | output | | | | 17 | 50 | ns |

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

NOTE 5: This parameter is applicable at one V_{CC} and operating temperature within the recommended operating conditions and to any two devices.

driver switching characteristics over recommended operating conditions (unless otherwise noted)

| | DADAMETED | | TEST CO | TEST CONDITIONS | | SN55976A | | |
|----------------------|---|-----------|---------------------|-----------------------|-----|------------------|------|------|
| | PARAMETER | | TEST CONDITIONS | | MIN | TYP [†] | MAX | UNIT |
| | Propagation delay time, tpHL or tpLH | | $V_{CC} = 5 V$, | T _A = 25°C | | | 15 | ns |
| ^t pd | (see Figures 1 and 2) | '976A2 | $V_{CC} = 5 V$, | T _A = 25°C | | | 13.5 | ns |
| | Skew limit, maximum t _{pd} – minimum t _{pd} | | | | | | 8 | ns |
| ^t sk(lim) | (300 14010 3) | '976A2 | | | | | 4 | ns |
| t _{sk(p)} | Pulse skew, tpHL - tpLH | | | | | | 4 | ns |
| t _f | Fall time | | S1 to B, | See Figure 2 | | 4 | | ns |
| t _r | Rise time | | See Figure 2 | | | 8 | | ns |
| t _{en} | Enable time, control inputs to active output | | | | | | 60 | ns |
| ^t dis | Disable time, control inputs to high-impedance output | ıt | | | | | 140 | ns |
| ^t PHZ | Propagation delay time, high-level to high-impedance | e output | | | | | 120 | ns |
| ^t PLZ | t _{PLZ} Propagation delay time, low-level to high-impedance output | | 1 | | | | 120 | ns |
| ^t PZH | Propagation delay time, high-impedance to high-leve | el output | See Figures 5 and 6 | | | | 60 | ns |
| ^t PZL | Propagation delay time, high-impedance to low-level | output | | | | | 60 | ns |

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

NOTE 5. This parameter is applicable at one V_{CC} and operating temperature within the recommended operating conditions and to any two devices.



receiver switching characteristics over recommended operating conditions (unless otherwise noted)

| | PARAMETER | | TEST CO | MOITIONS | SN75976A | | | UNIT |
|----------------------|--|----------|------------------------|------------------------|----------|------|------|------|
| | PARAMETER | | TEST CONDITIONS | | MIN | TYP† | MAX | UNII |
| | | '976A1 | | | 7.5 | | 16.5 | ns |
| t _{pd} | Propagation delay time, tpHL or tpLH | | | | 8.5 | | 14.5 | ns |
| | (see Figures 3 and 4) | '976A2 | $V_{CC} = 5 V$, | T _C = 25°C | 8.6 | | 13.6 | ns |
| | | | V _{CC} = 5 V, | T _C = 100°C | 9 | | 14 | ns |
| | Skew limit, maximum t _{pd} – minimum t _{pd} | '976A1 | | | | | 9 | ns |
| ^t sk(lim) | (see Note 5) | '976A2 | | | | | 5 | ns |
| tsk(p) | Pulse skew, tpHL - tpLH | | | | | 0.6 | 4 | ns |
| t _t | Transition time (t _r or t _f) | | See Figure 4 | | | 2 | | ns |
| t _{en} | Enable time, control inputs to active output | | | | | | 50 | ns |
| t _{dis} | Disable time, control inputs to high-impedance output | ıt | | | | | 60 | ns |
| ^t PHZ | Propagation delay time, high-level to high-impedance | e output | | | | | 60 | ns |
| ^t PLZ | tPLZ Propagation delay time, low-level to high-impedance output | | See Figures 7 and 8 | | | | 50 | ns |
| ^t PZH | t _{PZH} Propagation delay time, high-impedance to high-level output | | | | | | 50 | ns |
| tPZL | Propagation delay time, high-impedance to low-level | output | | | | 50 | ns | |

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

NOTE 5. This parameter is applicable at one V_{CC} and operating temperature within the recommended operating conditions and to any two devices.

receiver switching characteristics over recommended operating conditions (unless otherwise noted)

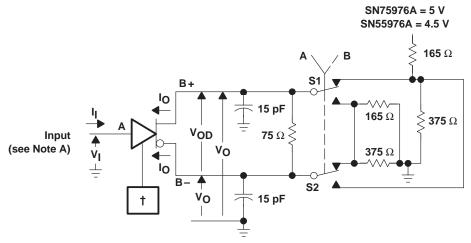
| | PARAMETER | | TEST CO | NDITIONS | s | N55976 <i>A</i> | 4 | UNIT |
|------------------|--|----------|---------------------|-----------------------|-----|-----------------|-----|------|
| | PARAMETER | | 1231 00 | MDITIONS | MIN | TYP† | MAX | UNII |
| | Propagation delay time, tpHL or tpLH | | $V_{CC} = 5 V$, | T _A = 25°C | | | 19 | ns |
| ^t pd | (see Figures 3 and 4) | '976A2 | $V_{CC} = 5 V$, | T _A = 25°C | | | 16 | ns |
| + \ | Skew limit, maximum t _{pd} – minimum t _{pd} | '976A1 | | | | | 9 | ns |
| tsk(lim) | tsk(lim) (see Note 5) | '976A2 | | | | | 5 | ns |
| tsk(p) | Pulse skew, tpHL - tpLH | | | | | 0.6 | 4 | ns |
| t _t | Transition time (t _f or t _f) | | See Figure 4 | | | 2 | | ns |
| ten | Enable time, control inputs to active output | | | | | | 70 | ns |
| tdis | Disable time, control inputs to high-impedance output | t | | - | | | 80 | ns |
| tPHZ | Propagation delay time, high-level to high-impedance | e output | | | | | 80 | ns |
| tPLZ | PLZ Propagation delay time, low-level to high-impedance output | | See Figures 7 and 8 | | | | 70 | ns |
| ^t PZH | | | | | | | 70 | ns |
| t _{PZL} | | | | | | | 70 | ns |

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

NOTE 5. This parameter is applicable at one V_{CC} and operating temperature within the recommended operating conditions and to any two devices.



PARAMETER MEASUREMENT INFORMATION



† CDE0 and DE/RE are at 2 V, BSR is at 0.8 V and, for the SN75976A only, all others are open.

[‡] For the SN75976A only, all nine drivers are enabled, similarly loaded, and switching.

Figure 1. Driver Test Circuit, Currents, and Voltages‡

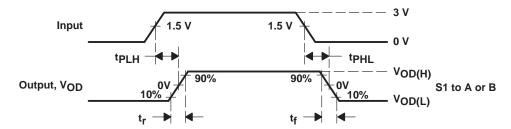
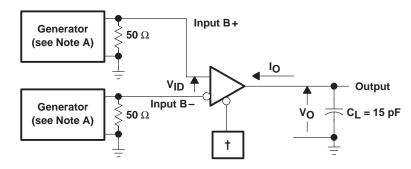


Figure 2. Driver Delay and Transition Time Test Waveforms



†CDE0, CDE1, CDE2, BSR, CRE, and DE/RE at 0.8 V

‡ For the SN75976A only, all nine receivers are enabled and switching.

Figure 3. Receiver Propagation Delay and Transition Time Test Circuit[‡]

NOTES: A. All input pulses are supplied by a generator having the following characteristics: $t_{\Gamma} \le 6$ ns, $t_{\Gamma} \le 6$ ns, PRR ≤ 1 MHz, duty cycle = 50%, $Z_{O} = 50 \Omega$.

- B. All resistances are in Ω and \pm 5%, unless otherwise indicated.
- C. All capacitances are in pF and \pm 10%, unless otherwise indicated.
- D. All indicated voltages are \pm 10 mV.



PARAMETER MEASUREMENT INFORMATION

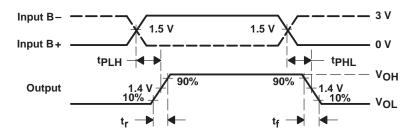
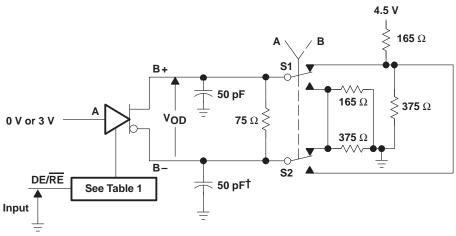


Figure 4. Receiver Delay and Transition Time Waveforms



† Includes probe and jig capacitance in two places.

Figure 5. Driver Enable and Disable Time Test Circuit

Table 1. Enabling For Driver Enable And Disable Time

| DRIVER | BSR | CDE0 | CDE1 | CDE2 | CRE |
|--------|-----|------|------|------|-----|
| 1 – 8 | Н | Н | L | L | Х |
| 9 | L | Н | Н | Н | Н |

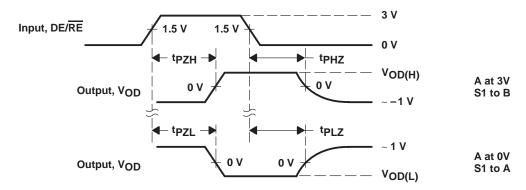
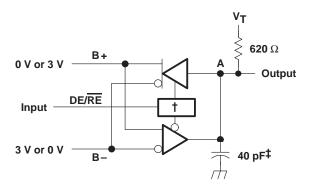


Figure 6. Driver Enable Time Waveforms

- NOTES: A. All input pulses are supplied by a generator having the following characteristics: $t_{\Gamma} \le 6$ ns, $t_{\tilde{f}} \le 6$ ns, PRR ≤ 1 MHz, duty cycle = 50%, $Z_{\tilde{O}} = 50 \Omega$.
 - B. All resistances are in Ω and \pm 5%, unless otherwise indicated.
 - C. All capacitances are in pF and \pm 10%, unless otherwise indicated.
 - D. All indicated voltages are $\pm\,10$ mV.



PARAMETER MEASUREMENT INFORMATION



[†] CDE0 is high, CDE1, CDE2, BSR, and CRE are low and, for the SN75976A only, all others are open.

Figure 7. Receiver Enable and Disable Time Test Circuit

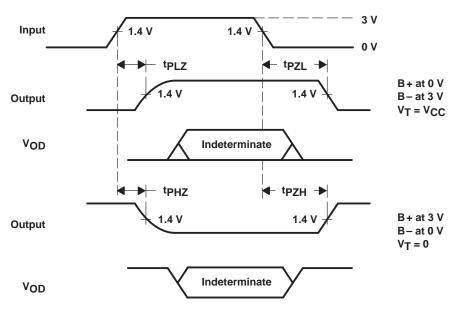
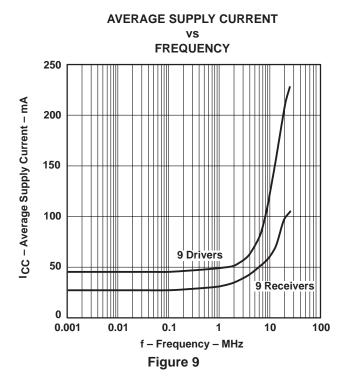


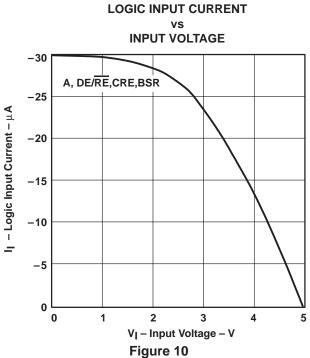
Figure 8. Receiver Enable and Disable Time Waveforms

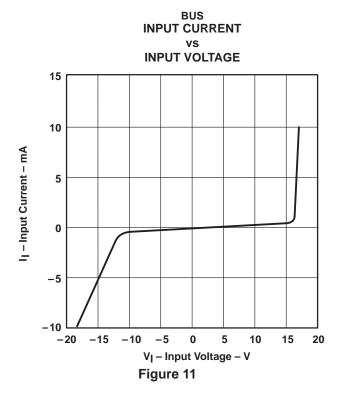
- NOTES: A. All input pulses are supplied by a generator having the following characteristics: $t_f \le 6$ ns, $t_f \le 6$ ns, PRR ≤ 1 MHz, duty cycle = 50%, $Z_O = 50 \Omega$.
 - B. All resistances are in Ω and \pm 5%, unless otherwise indicated.
 - C. All capacitances are in pF and \pm 10%, unless otherwise indicated.
 - D. All indicated voltages are \pm 10 mV.

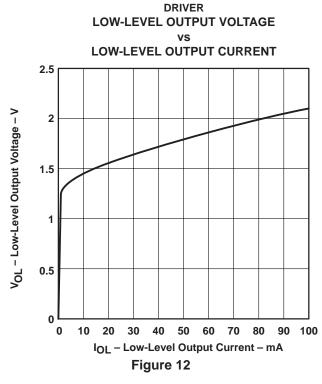
[‡] Includes probe and jig capacitance.

TYPICAL CHARACTERISTICS

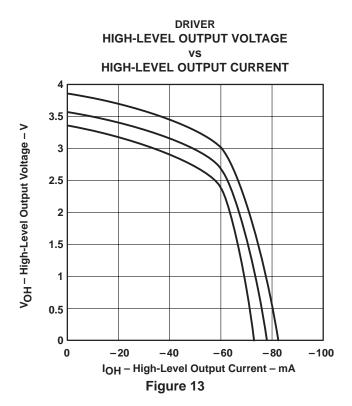


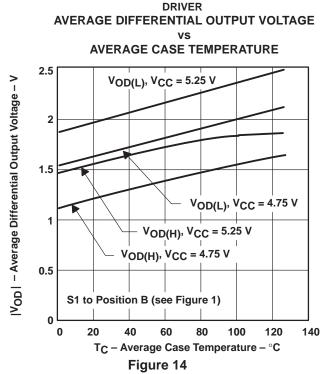


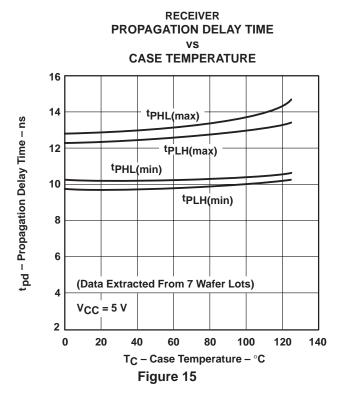


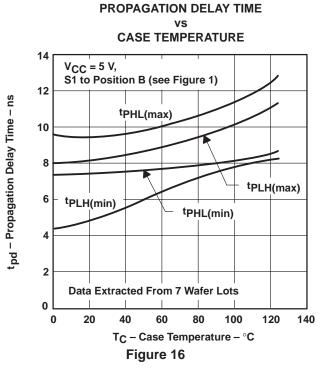


TYPICAL CHARACTERISTICS









DRIVER

TYPICAL CHARACTERISTICS

DRIVER
OUTPUT CURRENT
VS
SUPPLY VOLTAGE

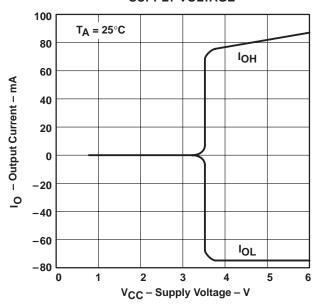


Figure 17

Table 2. Typical Signal and Terminal Assignments

| SIGNAL | TERMINAL | SCSI DATA | SCSI CONTROL | IPI DATA | IPI CONTROL |
|--------|----------|--------------|--------------|------------|--------------|
| CDE0 | 54 | DIFFSENSE | DIFFSENSE | VCC | VCC |
| CDE1 | 55 | GND | GND | XMTA, XMTB | GND |
| CDE2 | 56 | GND | GND | XMTA, XMTB | SLAVE/MASTER |
| BSR | 2 | GND | GND | GND, BSR | GND |
| CRE | 3 | GND | GND | GND | VCC |
| 1A | 4 | DB0, DB8 | ATN | AD7, BD7 | NOT USED |
| 1DE/RE | 5 | DBE0, DBE8 | INIT EN | GND | GND |
| 2A | 6 | DB1, DB9 | BSY | AD6, BD6 | NOT USED |
| 2DE/RE | 7 | DBE1, DBE9 | BSY EN | GND | GND |
| ЗА | 8 | DB2, DB10 | ACK | AD5, BD5 | SYNC IN |
| 3DE/RE | 9 | DBE2, DBE10 | INIT EN | GND | GND |
| 4A | 10 | DB3, DB11 | RST | AD4, BD4 | SLAVE IN |
| 4DE/RE | 11 | DBE3, DBE11 | GND | GND | GND |
| 5A | 19 | DB4, DB12 | MSG | AD3, BD3 | NOT USED |
| 5DE/RE | 20 | DBE4, DBE12 | TARG EN | GND | GND |
| 6A | 21 | DB5, DB13 | SEL | AD2, BD2 | SYNC OUT |
| 6DE/RE | 22 | DBE5, DBE13 | SEL EN | GND | GND |
| 7A | 23 | DB6, DB14 | C/D | AD1, BD1 | MASTER OUT |
| 7DE/RE | 24 | DBE6, DBE14 | TARG EN | GND | GND |
| 8A | 25 | DB7, DB15 | REQ | AD0, BD0 | SELECT OUT |
| 8DE/RE | 26 | DBE7, DBE15 | TARG EN | GND | GND |
| 9A | 27 | DBP0, DBP1 | I/O | AP, BP | ATTENTION IN |
| 9DE/RE | 28 | DBPE0, DBPE1 | TARG EN | XMTA, XMTB | Vcc |

ABBREVIATIONS:

 $DBn = data \ bit \ n, \ where \ n = (0,1, \ \dots, 15)$

DBEn = data bit n enable, where $n = (0,1, \dots, 15)$

DBP0 = parity bit for data bits 0 through 7 or IPI bus A

DBPE0 = parity bit enable for P0

DBP1 = parity bit for data bits 8 through 15 or IPI bus B

DBPE1 = parity bit enable for P1

ADn or BDn = IPI Bus A – Bit n (ADn) or Bus B – Bit n (BDn), where n = (0,1, \dots ,7)

AP or BP = IPI parity bit for bus A or bus B

XMTA or XMTB = transmit enable for IPI bus A or B

BSR = bit significant response

INIT EN = common enable for SCSI initiator mode

TARG EN = common enable for SCSI target mode

NOTE A: Signal inputs are shown as active high. When only active-low inputs are available, logic inversion is accomplished by reversing the B+ and B- connector terminal assignments.



Function Tables

RECEIVER



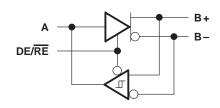
| INP | OUTPUT | |
|-----|--------|---|
| B+† | в-† | Α |
| L | Н | L |
| H | L | Н |

DRIVER



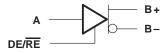
| INPUT | OUTPUTS | | | | |
|-------|---------|---|--|--|--|
| Α | B+ B- | | | | |
| L | L | Н | | | |
| Н | Н | L | | | |

TRANSCEIVER



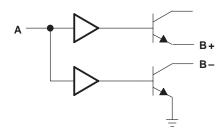
| | INPU | ITS | | C | UTPU | TS |
|-------|------|-----|-----|---|------|----|
| DE/RE | Α | B+† | в-† | Α | B+ | B- |
| L | _ | L | Н | L | _ | _ |
| L | _ | Н | L | Н | _ | - |
| н | L | _ | _ | - | L | Н |
| Н | Н | _ | _ | - | Н | L |

DRIVER WITH ENABLE



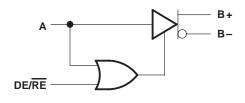
| INPUT | rs | OUTP | UTS |
|-------|----|------|-----|
| DE/RE | Α | B+ | B- |
| L | L | Z | Z |
| L | Н | Z | Z |
| Н | L | L | Н |
| Н | Н | Н | L |

WIRED-OR DRIVER



| INPUT | OUTF | PUTS |
|-------|------|------|
| Α | B+ | B- |
| L | Z | Z |
| Н | Н | L |

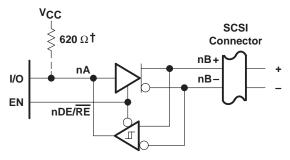
TWO-ENABLE INPUT DRIVER



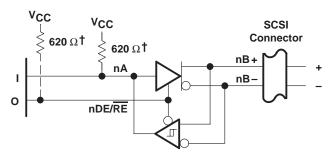
| INPUT | rs | OUTPUTS | | | | |
|-------|----|---------|----|--|--|--|
| DE/RE | Α | B+ | B- | | | |
| L | L | Z | Z | | | |
| L | Н | Н | L | | | |
| Н | L | L | Н | | | |
| Н | Н | Н | L | | | |

H = high level, L = low level, X = irrelevant, Z = high impedance (off)

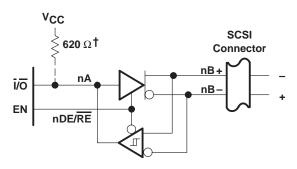
[†] An H in this column represents a voltage of 200 mV or higher than the other bus input. An L represents a voltage of 200 mV or lower than the other bus input. Any voltage less than 200 mV results in an indeterminate receiver output.



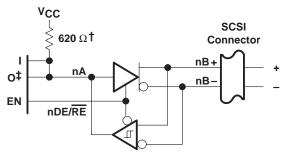
(a) ACTIVE-HIGH BIDIRECTIONAL I/O WITH SEPARATE ENABLE



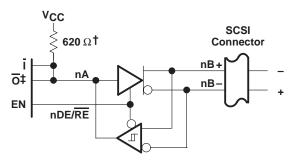
(c) WIRED-OR DRIVER AND ACTIVE-HIGH INPUT



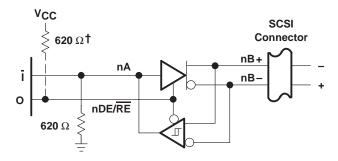
(b) ACTIVE-LOW BIDIRECTIONAL I/O WITH SEPARATE ENABLE



(d) SEPARATE ACTIVE-HIGH INPUT, OUTPUT, AND ENABLE



(e) SEPARATE ACTIVE-LOW INPUT AND OUTPUT AND ACTIVE-HIGH ENABLE



(f) WIRED-OR DRIVER AND ACTIVE-LOW INPUT

NOTE A: The BSR, CRE, A, and DE/RE inputs have internal pullup resistors. CDE0, CDE1, and CDE2 have internal pulldown resistors.

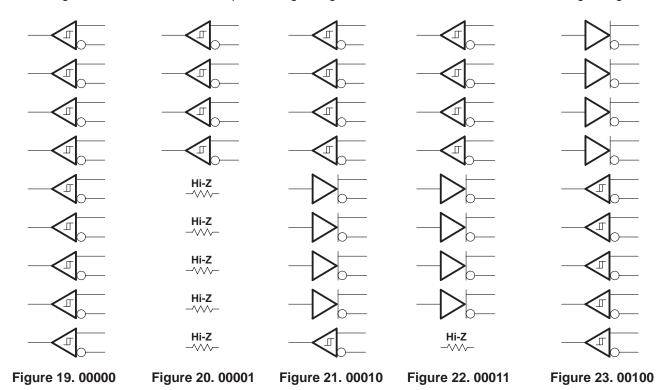
Figure 18. Typical SCSI Transceiver Connections

[†]When 0 is open drain

[‡] Must be open-drain or 3-state output

channel logic configurations with control input logic

The following logic diagrams show the positive-logic representation for all combinations of control inputs. The control inputs are from MSB to LSB; the BSR, CDE0, CDE1, CDE2, and CRE bit values are shown below the diagrams. Channel 1 is at the top of the logic diagrams; channel 9 is at the bottom of the logic diagrams.



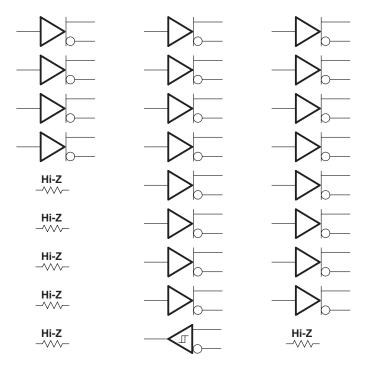


Figure 25. 00110 Figure 26. 00111 Figure 24. 00101

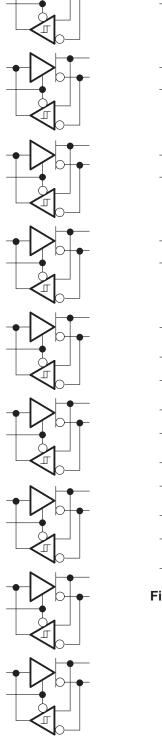
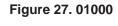
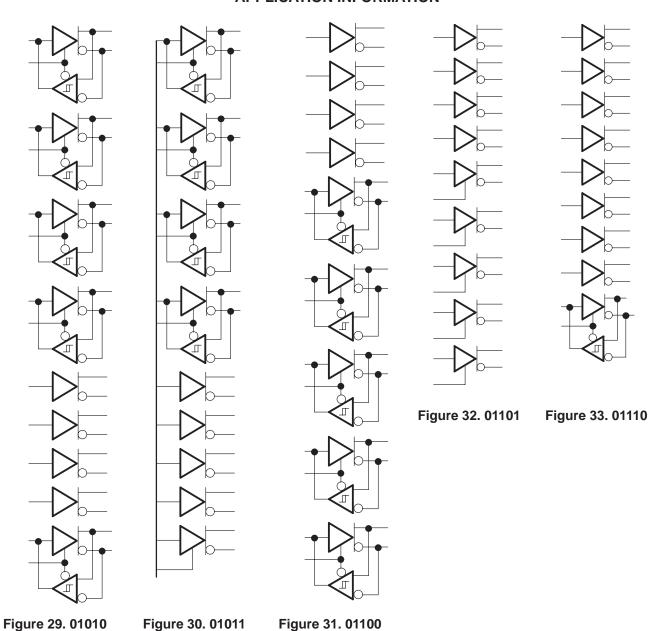


Figure 28. 01001







Hi-Z

Hi-Z

-^^^

Hi-Z

-^^

Hi-Z

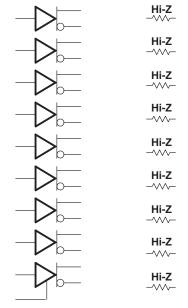


Figure 34. 01111



Hi-Z

Figure 36. 10010 and 10011

-^^

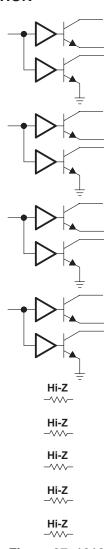


Figure 37. 10100 and 10101

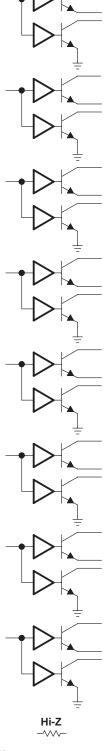


Figure 38. 10110 and 10111



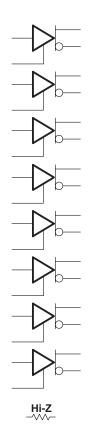


Figure 39. 11000 and 11001

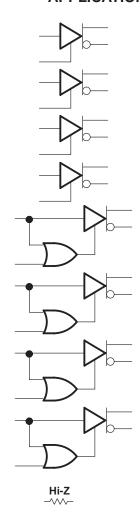


Figure 40. 11010 and 11011

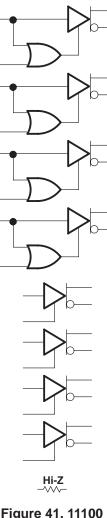


Figure 41. 11100 and 11101

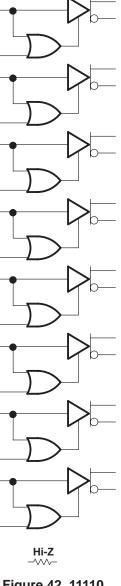


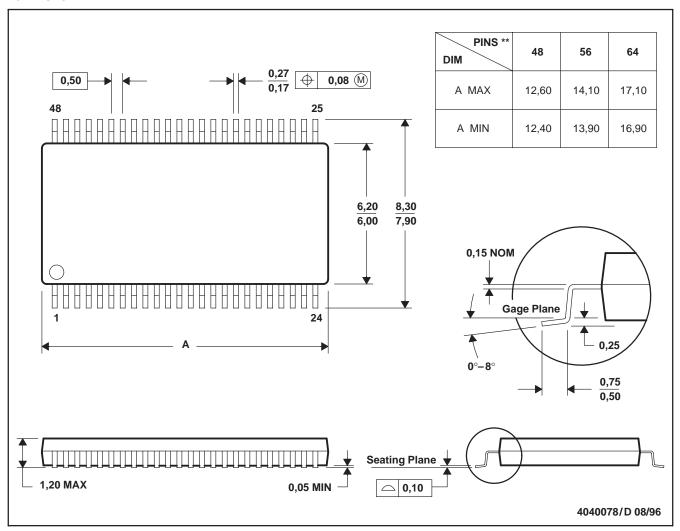
Figure 42. 11110 and 11111

MECHANICAL INFORMATION

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PIN SHOWN



NOTES: B. All linear dimensions are in millimeters.

C. This drawing is subject to change without notice.

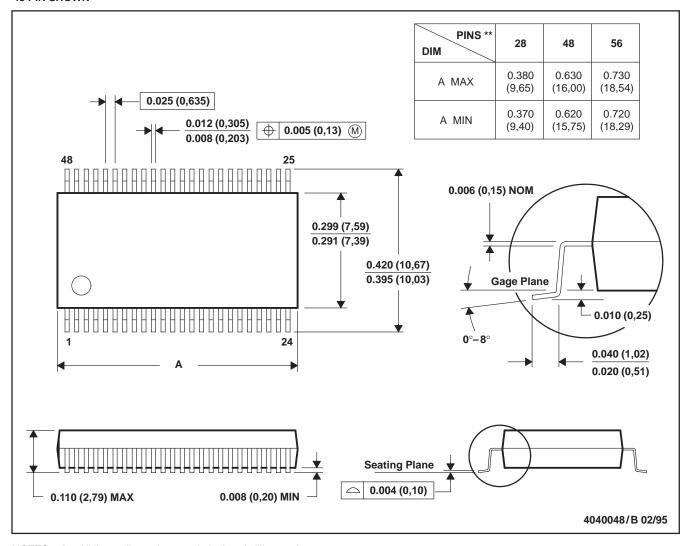
D. Falls within JEDEC MO-153

MECHANICAL INFORMATION

DL (R-PDSO-G**)

48 PIN SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

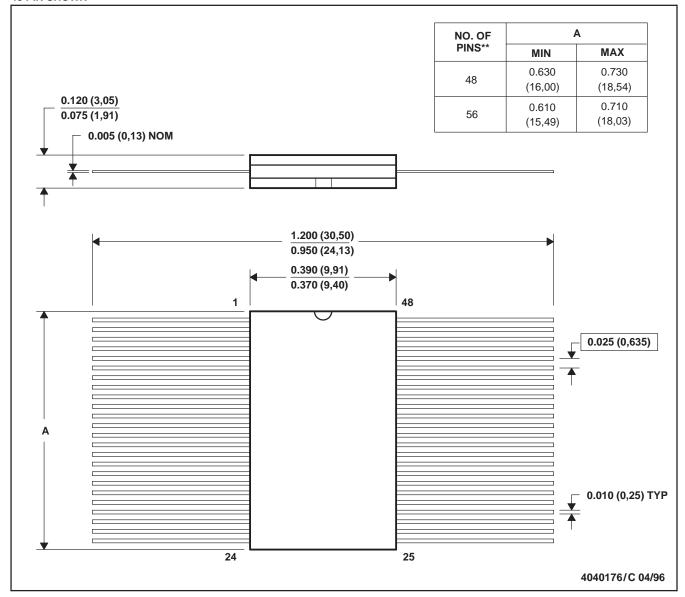
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

MECHANICAL INFORMATION

WD (R-GDFP-F**)

CERAMIC DUAL FLATPACK

48 PIN SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for pin identification only
- E. Falls within MIL-STD-1835: GDFP1-F48 and JEDEC MO-146AA GDFP1-F56 and JEDEC MO-146AB



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PACKAGING INFORMATION

| Orderable part number | Status (1) | Material type | Package Pins | Package qty Carrier | RoHS (3) | Lead finish/ Ball material | MSL rating/ Peak reflow | Op temp (°C) | Part marking (6) |
|-----------------------|------------|---------------|------------------|-----------------------|-----------------|-------------------------------|----------------------------|--------------|-------------------------------------|
| 5962-9689301QXA | Active | Production | CFP (WD) 56 | 15 TUBE | No | SNPB | N/A for Pkg Type | -55 to 125 | 5962-9689301QX A SNJ55976A1WD |
| SN55976A1WD | Active | Production | CFP (WD) 56 | 15 TUBE | No | SNPB | N/A for Pkg Type | -55 to 125 | SN55976A1WD |
| SN75976A1DGG | Active | Production | TSSOP (DGG) 56 | 35 TUBE | Yes | NIPDAU | Level-2-260C-1 YEAR | - | SN75976A1 |
| SN75976A1DL | Active | Production | SSOP (DL) 56 | 20 TUBE | Yes | NIPDAU | Level-2-260C-1 YEAR | - | SN75976A1 |
| SN75976A1DLR | Active | Production | SSOP (DL) 56 | 1000 LARGE T&R | Yes | NIPDAU | Level-2-260C-1 YEAR | - | SN75976A1 |
| SN75976A2DGG | Active | Production | TSSOP (DGG) 56 | 35 TUBE | Yes | NIPDAU | Level-2-260C-1 YEAR | 0 to 70 | SN75976A2 |
| SN75976A2DGGR | Active | Production | TSSOP (DGG) 56 | 2000 LARGE T&R | Yes | NIPDAU | Level-2-260C-1 YEAR | - | SN75976A2 |
| SN75976A2DL | Active | Production | SSOP (DL) 56 | 20 TUBE | Yes | NIPDAU | Level-2-260C-1 YEAR | - | SN75976A2 |
| SN75976A2DLR | Active | Production | SSOP (DL) 56 | 1000 LARGE T&R | Yes | NIPDAU | Level-2-260C-1 YEAR | - | SN75976A2 |
| SNJ55976A1WD | Active | Production | CFP (WD) 56 | 15 TUBE | No | SNPB | N/A for Pkg Type | -55 to 125 | 5962-9689301QX A SNJ55976A1WD |

⁽¹⁾ Status: For more details on status, see our product life cycle.

⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.



PACKAGE OPTION ADDENDUM

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Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN55976A, SN75976A:

Catalog: SN75976A

Enhanced Product: SN75976A-EP, SN75976A-EP

Military: SN55976A

NOTE: Qualified Version Definitions:

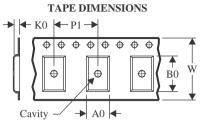
- Catalog TI's standard catalog product
- Enhanced Product Supports Defense, Aerospace and Medical Applications
- Military QML certified for Military and Defense Applications



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TAPE AND REEL INFORMATION

REEL DIMENSIONS Reel Diameter Reel Width (W1)



| _ | Tanana and a same and a same and a same and a same a s |
|----|--|
| A0 | Dimension designed to accommodate the component width |
| В0 | Dimension designed to accommodate the component length |
| K0 | Dimension designed to accommodate the component thickness |
| W | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



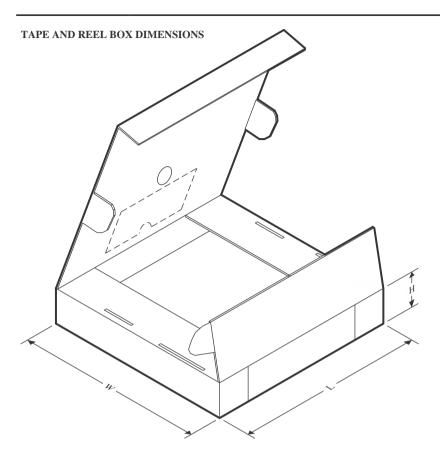
*All dimensions are nominal

| Device | Package Type | Package Drawing | | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|---------------|-----------------|--------------------|----|------|--------------------------|--------------------------|------------|------------|------------|------------|-----------|------------------|
| SN75976A1DLR | SSOP | DL | 56 | 1000 | 330.0 | 32.4 | 11.35 | 18.67 | 3.1 | 16.0 | 32.0 | Q1 |
| SN75976A2DGGR | TSSOP | DGG | 56 | 2000 | 330.0 | 24.4 | 8.6 | 15.6 | 1.8 | 12.0 | 24.0 | Q1 |
| SN75976A2DLR | SSOP | DL | 56 | 1000 | 330.0 | 32.4 | 11.35 | 18.67 | 3.1 | 16.0 | 32.0 | Q1 |



PACKAGE MATERIALS INFORMATION

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*All dimensions are nominal

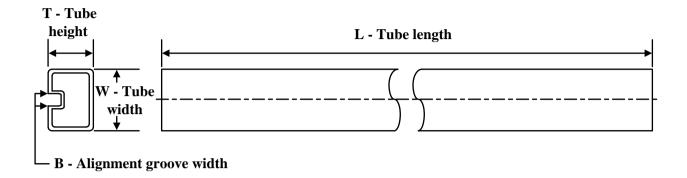
| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|---------------|--------------|-----------------|------|------|-------------|------------|-------------|
| SN75976A1DLR | SSOP | DL | 56 | 1000 | 367.0 | 367.0 | 55.0 |
| SN75976A2DGGR | TSSOP | DGG | 56 | 2000 | 367.0 | 367.0 | 45.0 |
| SN75976A2DLR | SSOP | DL | 56 | 1000 | 367.0 | 367.0 | 55.0 |





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TUBE



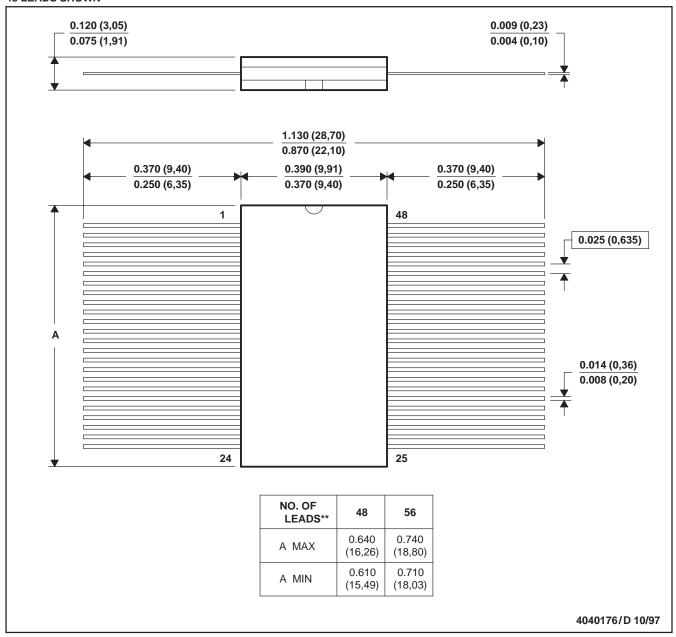
*All dimensions are nominal

| Device | Package Name | Package Type | Pins | SPQ | L (mm) | W (mm) | T (µm) | B (mm) |
|--------------|--------------|--------------|------|-----|--------|--------|--------|--------|
| SN75976A1DGG | DGG | TSSOP | 56 | 35 | 530 | 11.89 | 3600 | 4.9 |
| SN75976A1DL | DL | SSOP | 56 | 20 | 473.7 | 14.24 | 5110 | 7.87 |
| SN75976A2DGG | DGG | TSSOP | 56 | 35 | 530 | 11.89 | 3600 | 4.9 |
| SN75976A2DL | DL | SSOP | 56 | 20 | 473.7 | 14.24 | 5110 | 7.87 |

WD (R-GDFP-F**)

CERAMIC DUAL FLATPACK

48 LEADS SHOWN



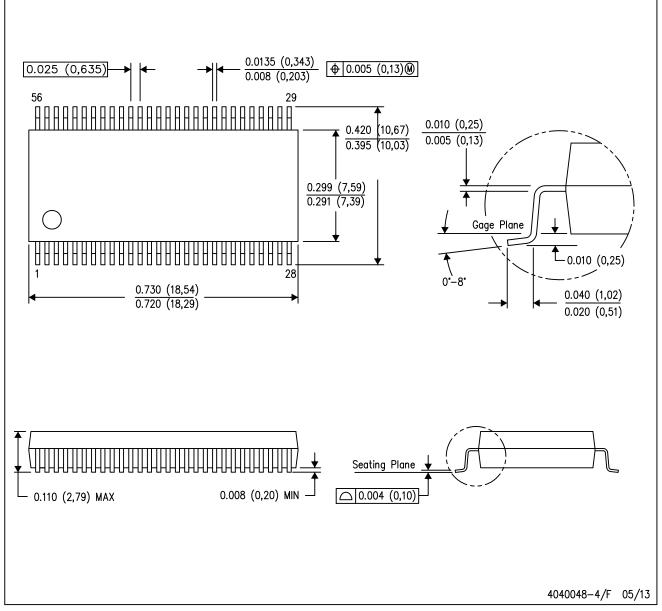
NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only
- E. Falls within MIL STD 1835: GDFP1-F48 and JEDEC MO-146AA GDFP1-F56 and JEDEC MO-146AB



DL (R-PDSO-G56)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

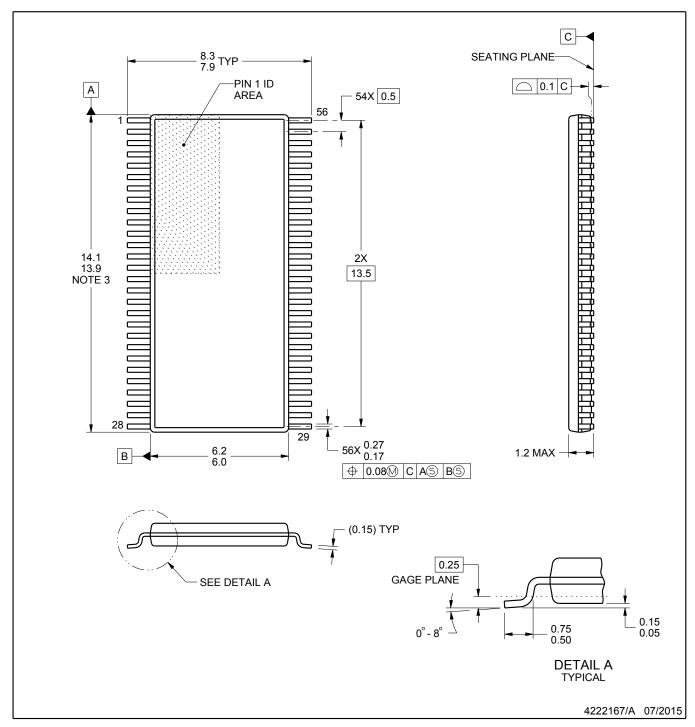
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MO-118

PowerPAD is a trademark of Texas Instruments.





SMALL OUTLINE PACKAGE



NOTES:

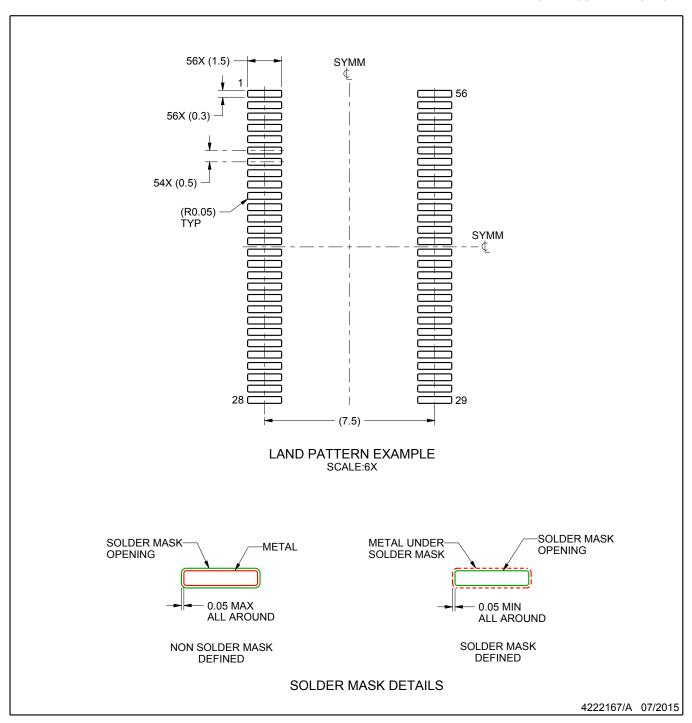
- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
 4. Reference JEDEC registration MO-153.



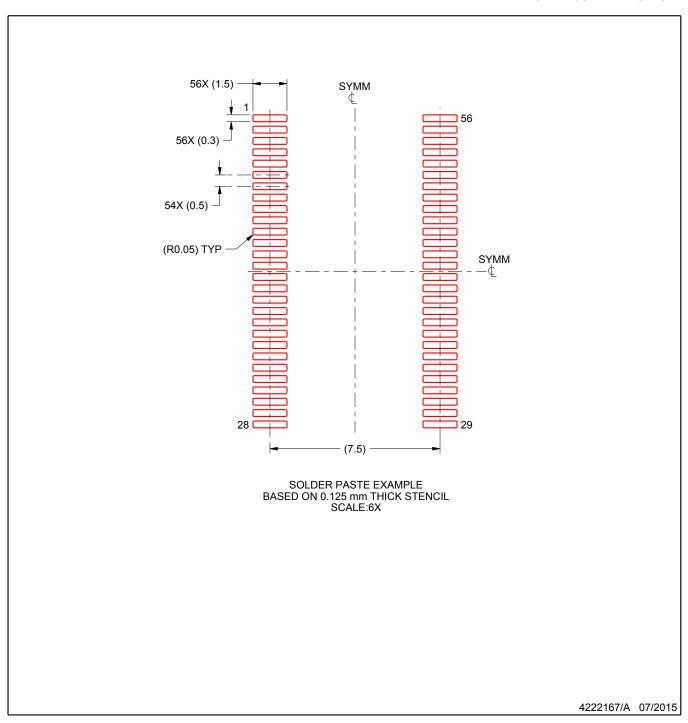
SMALL OUTLINE PACKAGE



NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

SMALL OUTLINE PACKAGE



NOTES: (continued)

- Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.



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